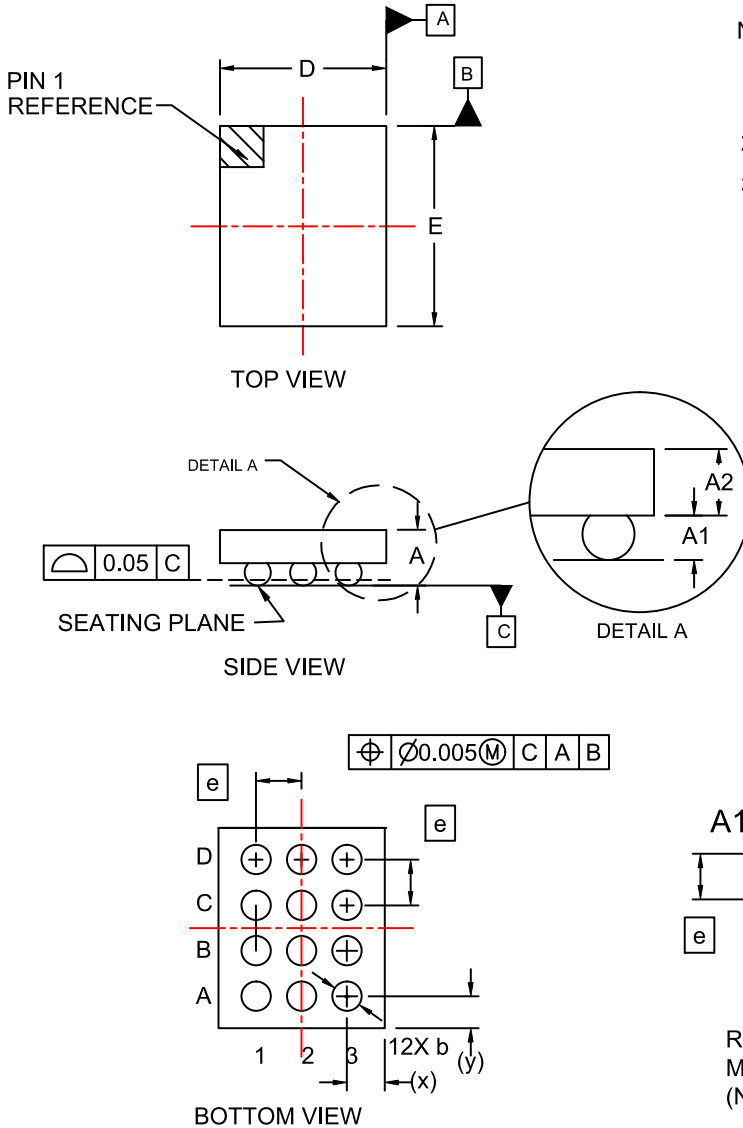




**WLCSP12, 1.21x1.67x0.586**  
**CASE 567VZ**  
**ISSUE O**

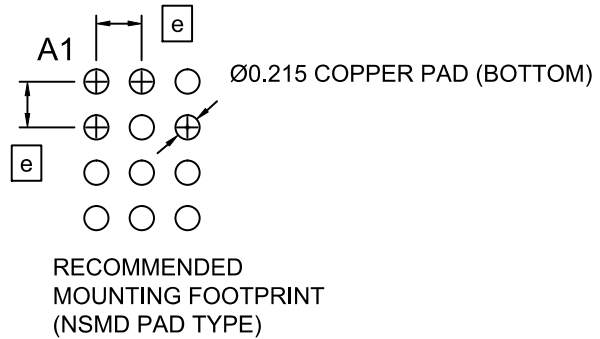
DATE 09 FEB 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	.536	.574	.612
A1	.176	.196	.216
A2	.360	.378	.396
b	.240	.260	.280
D	1.18	1.21	1.24
E	1.64	1.67	1.70
e	0.40 BSC		
x	0.190	0.205	0.220
y	0.220	0.235	0.250



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